

MECHANICAL CASE OUTLINE

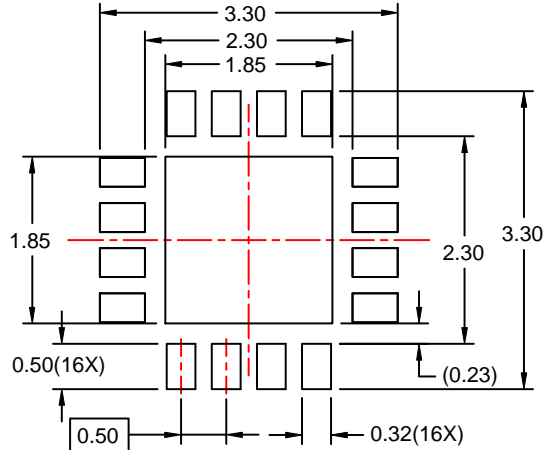
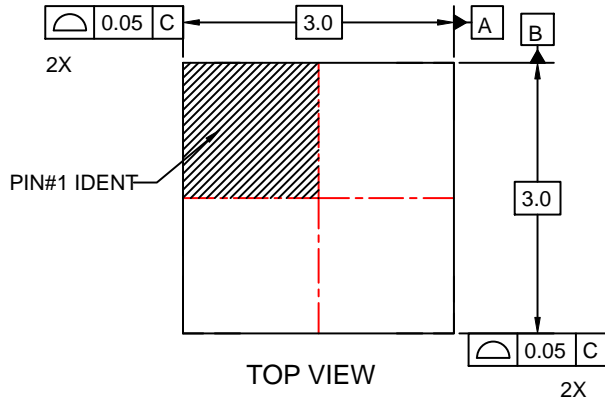
PACKAGE DIMENSIONS

ON Semiconductor®

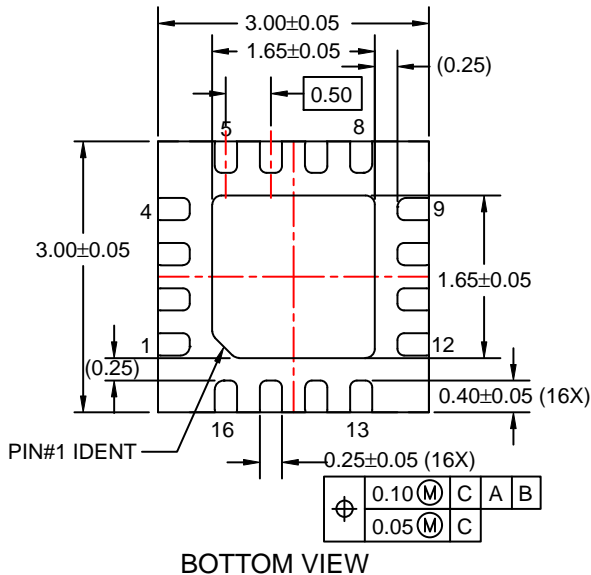
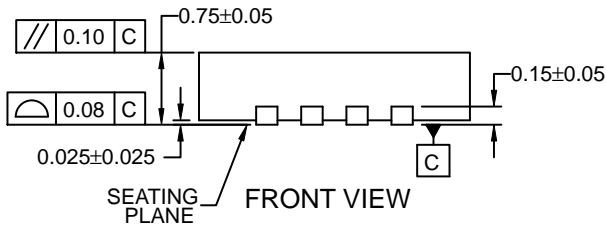


WQFN16 3x3, 0.5P
CASE 511DN
ISSUE A

DATE 21 MAR 2017



RECOMMENDED LAND PATTERN
PLEASE SEE NOTE "D"



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION, MO-220. VARIATION WEED-4.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS FOR REFERENCE ONLY, IT MAY NEED TO BE ADJUSTED TO MATCH YOUR SMT PROCESS CAPABILITIES.

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NEW STANDARD:		
DESCRIPTION:	WQFN16 3X3, 0.5P	PAGE 1 OF 2

